



Material Content Data Sheet



Sales Product Name		BSC019N06NS		Issued		4. July 2019		
MA#		MA005348645						
Package		PG-TDSON-8-48		Weight*		108.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.188	1.09	1.09	10925	10925
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		132	
	non noble metal	zinc	7440-66-6	0.057	0.05		527	
	non noble metal	iron	7439-89-6	1.145	1.05		10532	
wire	non noble metal	copper	7440-50-8	46.496	42.77	43.88	427649	438840
	noble metal	gold	7440-57-5	0.041	0.04	0.04	379	379
	encapsulation	organic material	carbon black	1333-86-4	0.083	0.08		764
plastics	plastics	epoxy resin	-	3.820	3.51		35138	
	inorganic material	silicondioxide	60676-86-0	37.623	34.60	38.19	346037	381939
	leadfinish	non noble metal	tin	7440-31-5	1.264	1.16	1.16	11623
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	267	267
solder	noble metal	silver	7440-22-4	0.041	0.04		378	
	non noble metal	tin	7440-31-5	0.082	0.08		756	
	non noble metal	lead	7439-92-1	1.520	1.40	1.52	13984	15118
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		42	
	non noble metal	zinc	7440-66-6	0.018	0.02		169	
	non noble metal	iron	7439-89-6	0.368	0.34		3382	
	non noble metal	copper	7440-50-8	14.930	13.73	14.09	137316	140909
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com